

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>TAKESHI TOKUYAMA</td> <td>11/01/2013</td> </tr> <tr> <td>KINYA NAKATSU</td> <td>11/05/2013</td> </tr> <tr> <td>RYUICHI SAITO</td> <td>11/11/2013</td> </tr> <tr> <td>TOSHIYA SATOH</td> <td>11/05/2013</td> </tr> <tr> <td>TOKIHITO SUWA</td> <td>11/05/2013</td> </tr> </tbody> </table>		Name	Execution Date	TAKESHI TOKUYAMA	11/01/2013	KINYA NAKATSU	11/05/2013	RYUICHI SAITO	11/11/2013	TOSHIYA SATOH	11/05/2013	TOKIHITO SUWA	11/05/2013
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CORRESPONDENCE DATA													
<p>Fax Number: (202)628-8844 Phone: 202-624-2500 Email: lbuckler@crowell.com <i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i> Correspondent Name: CROWELL & MORING LLP Address Line 1: 1001 PENNSYLVANIA AVENUE, NW Address Line 4: WASHINGTON, DISTRICT OF COLUMBIA 20004</p>													
ATTORNEY DOCKET NUMBER:	106734.66099US												
NAME OF SUBMITTER:	MICHAEL H. JACOBS												
Signature:	/Michael H. Jacobs/												
Date:	12/17/2013												
Total Attachments: 1 source=66099US-Assignment#page1.tif													

OP \$40.00 14126955

ASSIGNMENT
(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me by Hitachi Automotive Systems, Ltd., a corporation organized under the laws of Japan, located at 2520, Takaba, Hitachinaka-shi, Ibaraki Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi Automotive Systems, Ltd., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

POWER SEMICONDUCTOR MODULE AND POWER CONVERTER USING THE SAME

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Hitachi Automotive Systems, Ltd., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi Automotive Systems, Ltd.,

Signed on the date(s) indicated aside our signatures:

	INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1)	<u>Takeshi Tokuyama</u> Takeshi TOKUYAMA	<u>11/11/2013</u>
2)	<u>Kinya Nakatsu</u> Kinya NAKATSU	<u>11/5/2013</u>
3)	<u>Ryuichi Saito</u> Ryuichi SAITO	<u>11/11/2013</u>
4)	<u>Toshiya Satoh</u> Toshiya SATOH	<u>11/5/2013</u>
5)	<u>Tokihito Suwa</u> Tokihito SUWA	<u>11/5/2013</u>
6)	_____	_____
7)	_____	_____
8)	_____	_____
9)	_____	_____
10)	_____	_____